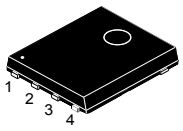
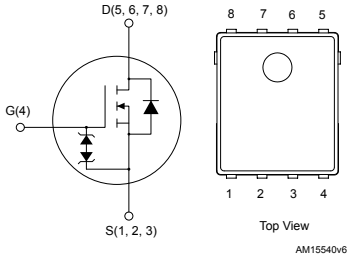
STL7LN65K5AG

Datasheet

Automotive-grade N-channel 650 V, 0.95 Ω typ., 5 A, MDmesh K5 Power MOSFET in a PowerFLAT 5x6 VHV package



PowerFLAT 5x6 VHV



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STL7LN65K5AG	650 V	1.15 Ω	5 A

- AEC-Q101 qualified
- Industry's lowest $R_{DS(on)}$ x area
- Industry's best FoM (figure of merit)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Product status link
STL7LN65K5AG

Product summary	
Order code	STL7LN65K5AG
Marking	7LN65K5
Package	PowerFLAT 5x6 VHV
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
I_D (1)	Drain current (continuous) at T_C = 25 °C	5	A
I_D (1)	Drain current (continuous) at T_C = 100 °C	3.4	A
I_D (2)	Drain current (pulsed)	20	A
P_{TOT}	Total power dissipation at T_C = 25 °C	79	W
dv/dt (3)	Peak diode recovery voltage slope	4.5	V/ns
dv/dt (4)	MOSFET dv/dt ruggedness	50	
T_{stg}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature range		

1. *Limited by maximum junction temperature.*
2. *Pulse width limited by safe operating area.*
3. *I_{SD} ≤ 5 A, di/dt 100 A/µs; V_{DS} peak < $V_{(BR)DSS}$, V_{DD}= 520 V.*
4. *V_{DS} ≤ 520 V.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJA}	Thermal resistance, junction-to-case	1.58	°C/W
R_{thJB} (1)	Thermal resistance, junction-to-board	59	°C/W

1. *When mounted on 1inch² FR-4 board, 2 oz Cu.*

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_{jmax})	1.5	A
E_{AS}	Single pulse avalanche energy (starting T_j = 25 °C, I_D = I_{AR}, V_{DD} = 50 V)	200	mJ

2 Electrical characteristics

T_C = 25 °C unless otherwise specified.

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	650			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 650 V			1	µA
		V_{GS} = 0 V, V_{DS} = 650 V, T_C = 125 °C (1)			50	µA
I_{GSS}	Gate-body leakage current	V_{DS} = 0 V, V_{GS} = ±20 V			±10	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D =100 µA	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 2.5 A		0.95	1.15	Ω

1. *Defined by design, not subject to production test.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS}= 100 V, f = 1 MHz, V_{GS} = 0 V	-	270	-	pF
C_{oss}	Output capacitance		-	22	-	pF
C_{rss}	Reverse transfer capacitance		-	0.5	-	pF
$C_{o(er)}$ (1)	Equivalent capacitance energy related	V_{DS} = 0 to 520 V, V_{GS} = 0 V	-	20	-	nC
$C_{o(tr)}$ (2)	Equivalent capacitance time related		-	57	-	nC
R_G	Intrinsic gate resistance	f = 1 MHz, I_D=0 A	-	7.5	-	Ω
Q_g	Total gate charge	V_{DD} = 520 V, I_D = 5 A, V_{GS} = 0 to 10 V (see Figure 14. Test circuit for gate charge behavior)	-	11.7	-	nC
Q_{gs}	Gate-source charge		-	2.7	-	nC
Q_{gd}	Gate-drain charge		-	7.3	-	nC

1. *Energy related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}*
2. *Time related is defined as a constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}*

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 300 V, I_D = 2.5 A R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	7.4	-	ns
t_r	Rise time		-	9.2	-	ns
$t_{d(off)}$	Turn-off delay time		-	19.8	-	ns
t_f	Fall time		-	16.4	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		5	A
I_{SDM} (1)	Source-drain current (pulsed)		-		20	A
V_{SD} (2)	Forward on voltage	I_{SD}= 5 A, V_{GS} = 0 V	-		1.6	V
t_{rr}	Reverse recovery time	I_{SD} = 5 A, di/dt = 100 A/µs, V_{DD} = 60 V (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	282		ns
Q_{rr}	Reverse recovery charge		-	1.97		µC
I_{RRM}	Reverse recovery current		-	14		A
t_{rr}	Reverse recovery time	I_{SD} = 5 A, di/dt = 100 A/µs, V_{DD} = 60 V, T_j = 150 °C (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	415		ns
Q_{rr}	Reverse recovery charge		-	2.70		µC
I_{RRM}	Reverse recovery current		-	13		A

1. *Pulse width is limited by safe operating area*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%*

Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	I_{GS} = ±1 mA, I_D = 0 A	30	-		V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection,thus eliminating the need for additional external componentry.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

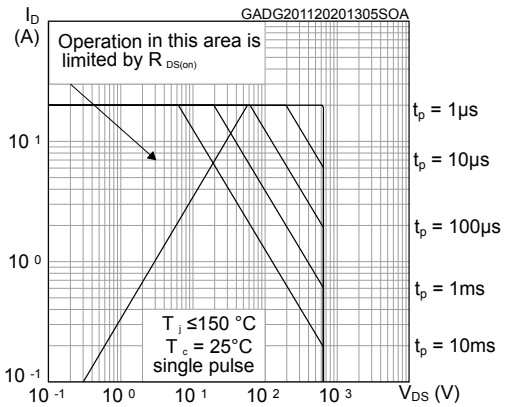


Figure 2. Maximum transient thermal impedance

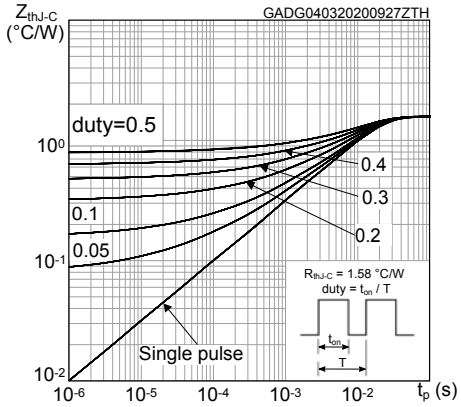


Figure 3. Typical output characteristics

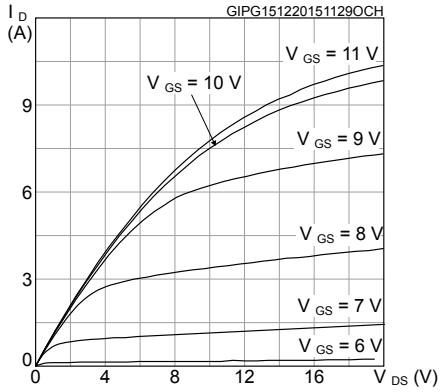


Figure 4. Typical transfer characteristics

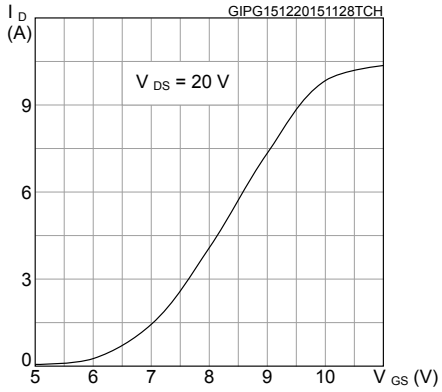


Figure 5. Typical gate charge characteristics

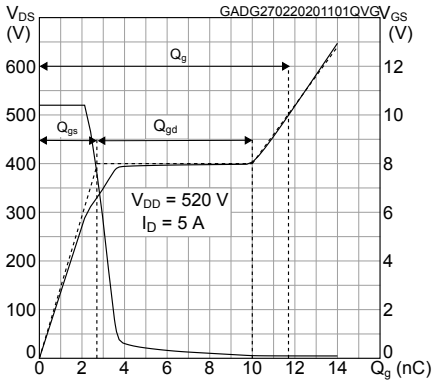


Figure 6. Typical drain-source on-resistance

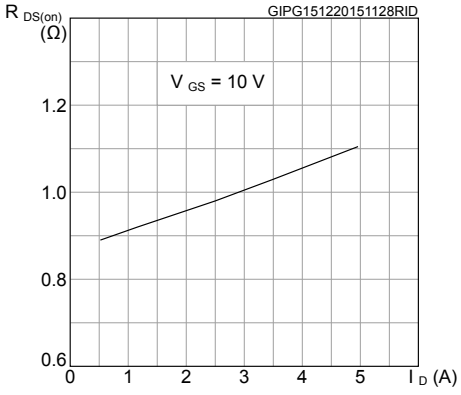


Figure 7. Typical capacitance characteristics

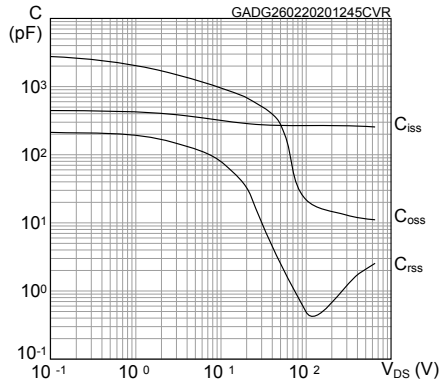


Figure 8. Normalized gate threshold vs temperature

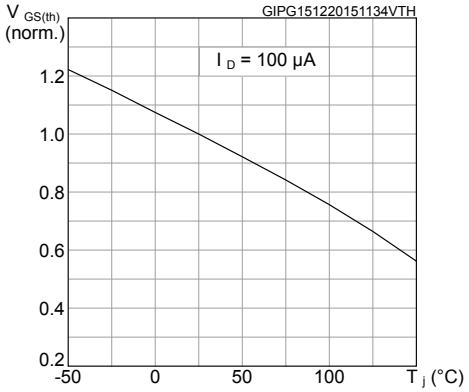


Figure 9. Normalized breakdown voltage vs temperature

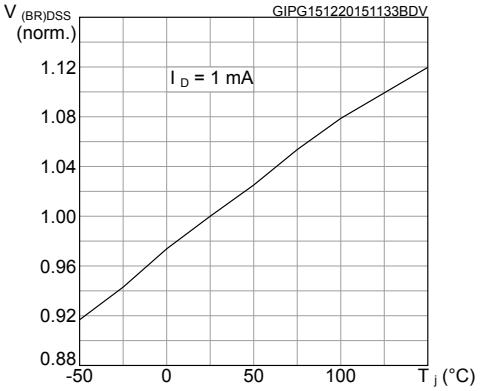


Figure 10. Normalized on-resistance vs temperature

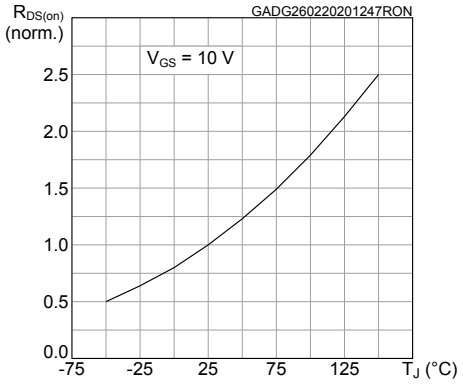


Figure 11. Typical reverse diode forward characteristics

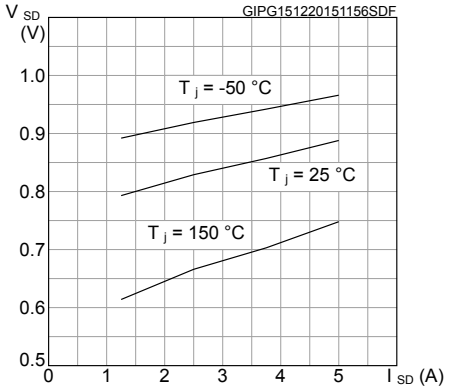
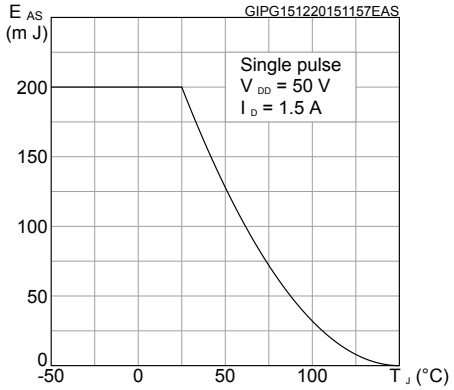


Figure 12. Maximum avalanche energy vs temperature



3 Test circuits

Figure 13. Test circuit for resistive load switching times

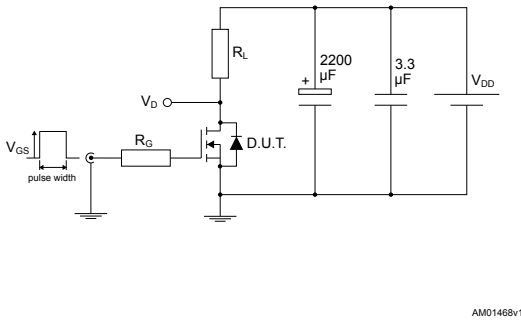


Figure 14. Test circuit for gate charge behavior

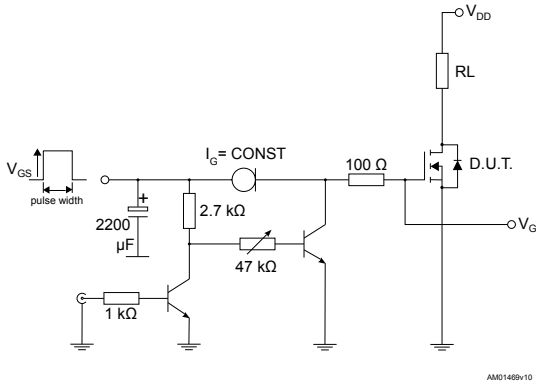


Figure 15. Test circuit for inductive load switching and diode recovery times

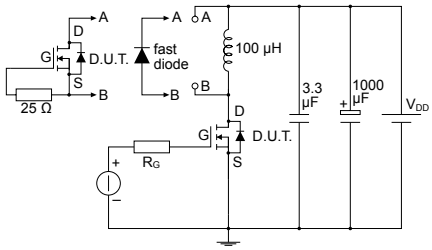


Figure 16. Unclamped inductive load test circuit

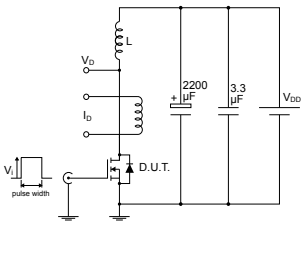


Figure 17. Unclamped inductive waveform

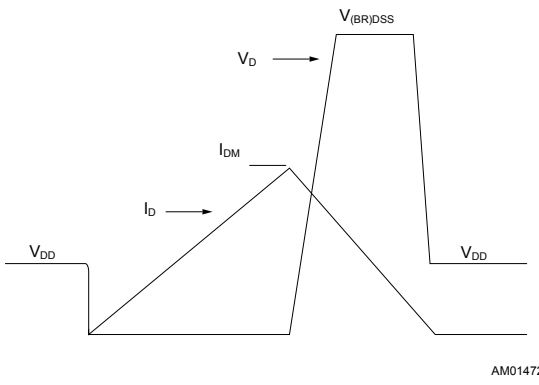
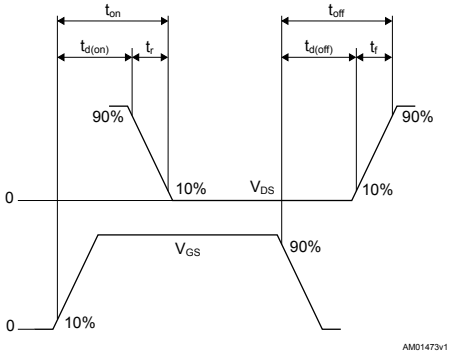


Figure 18. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 PowerFLAT 5x6 VHV mechanical data

Figure 19. **PowerFLAT 5x6 VHV package outline**

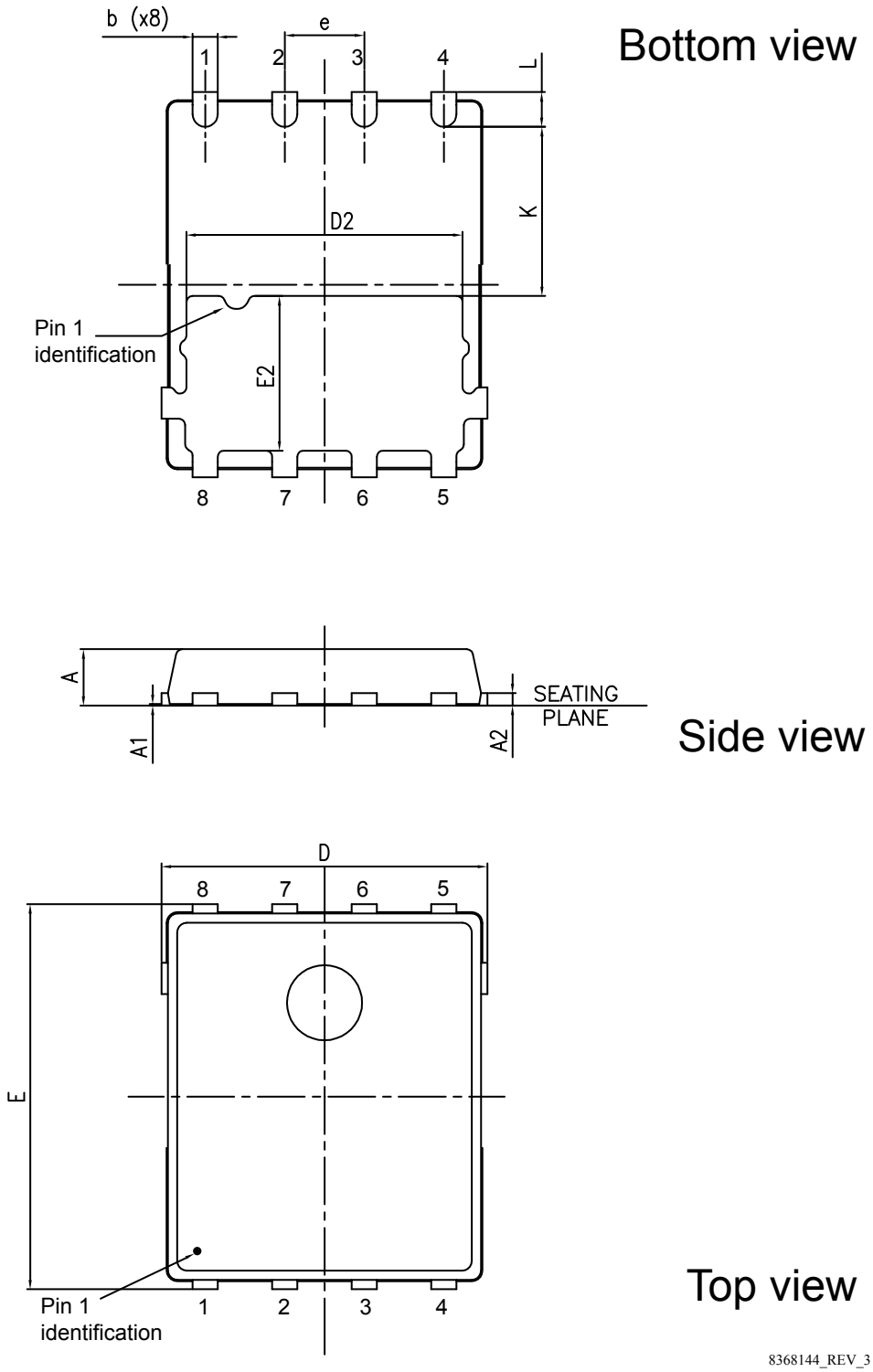
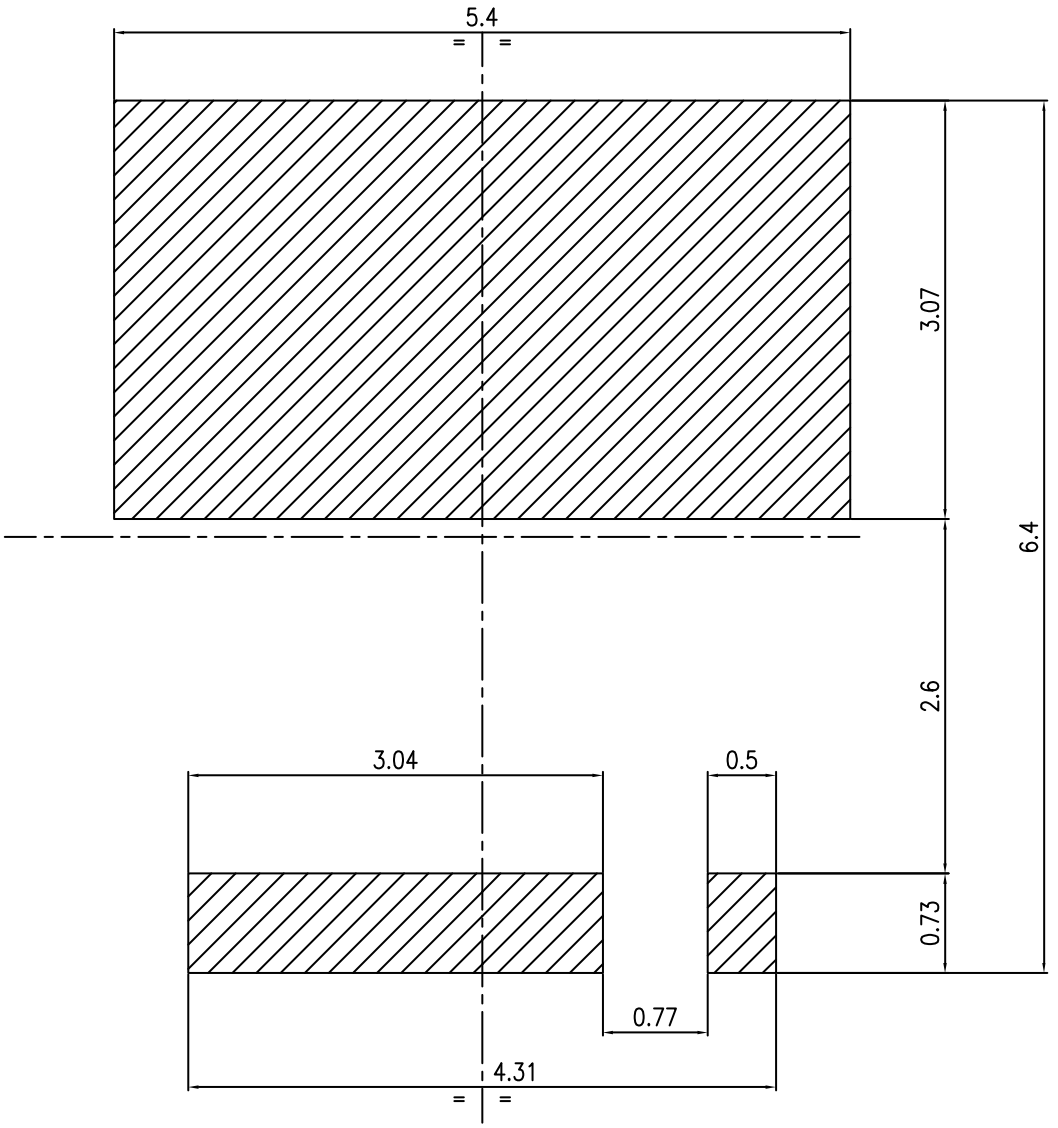


Table 9. PowerFLAT 5x6 VHV package mechanical data

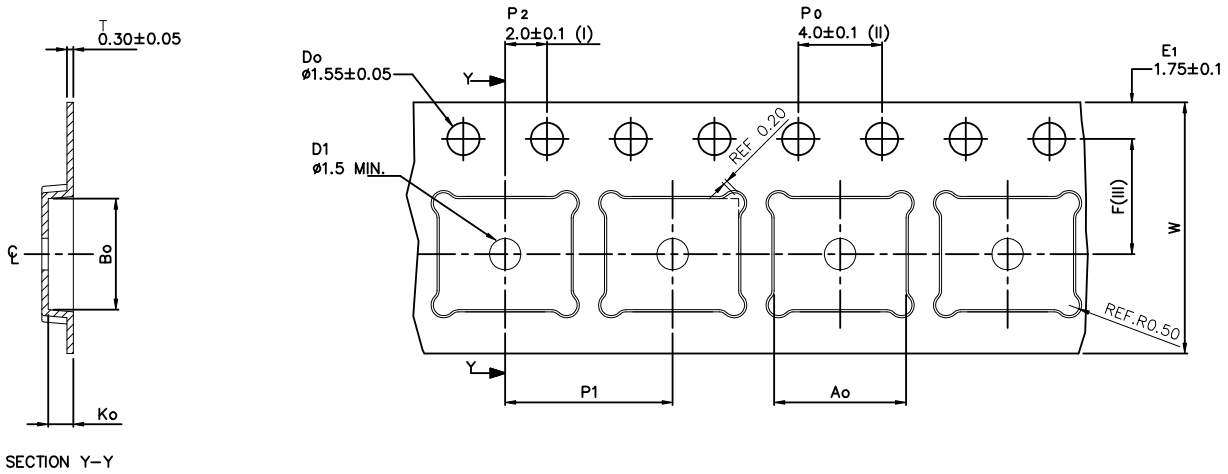
Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
D	5.00	5.20	5.40
E	5.95	6.15	6.35
D2	4.30	4.40	4.50
E2	2.40	2.50	2.60
e		1.27	
L	0.50	0.55	0.60
K	2.60	2.70	2.80

Figure 20. **PowerFLAT 5x6 VHV recommended footprint (dimensions are in mm)**



4.2 PowerFLAT 5x6 packing information

Figure 21. PowerFLAT 5x6 tape (dimensions are in mm)



Ao	6.30 +/– 0.1
Bo	5.30 +/– 0.1
Ko	1.20 +/– 0.1
F	5.50 +/– 0.1
P1	8.00 +/– 0.1
W	12.00 +/– 0.3

(I) Measured from centreline of sprocket hole to centreline of pocket.

(II) Cumulative tolerance of 10 sprocket holes is ±0.20.

(III) Measured from centreline of sprocket hole to centreline of pocket

Base and bulk quantity 3000 pcs
All dimensions are in millimeters

8234350_Tape_rev_C

Figure 22. PowerFLAT 5x6 package orientation in carrier tape

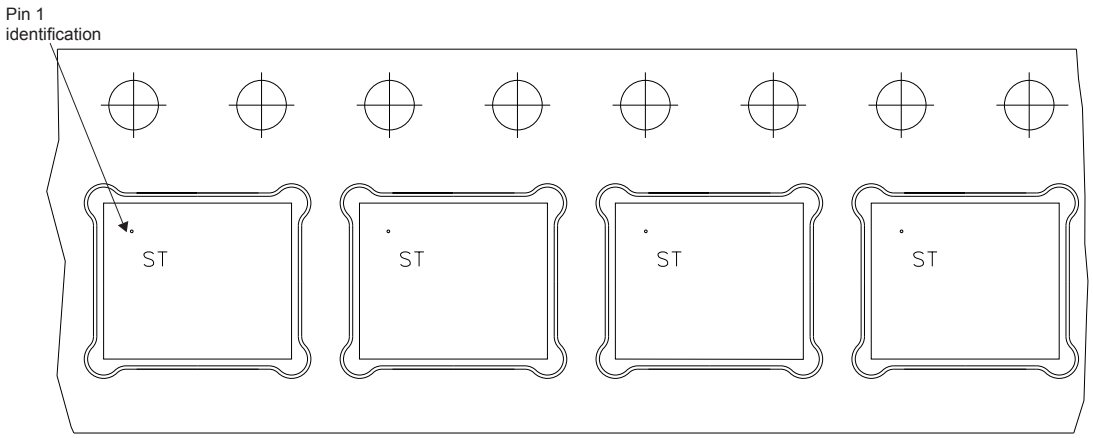
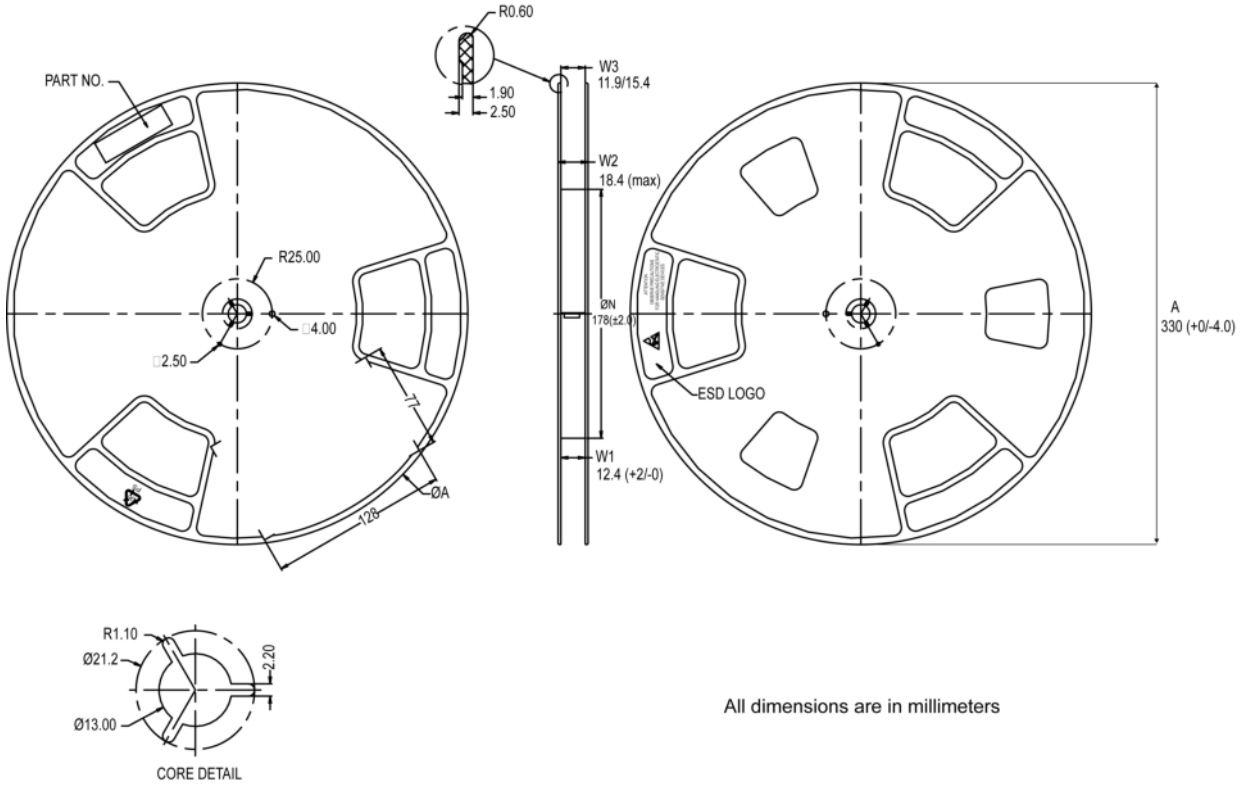


Figure 23. **PowerFLAT 5x6 reel**



Revision history

Table 10. **Document revision history**

Date	Version	Changes
04-Mar-2020	1	First release.
20-Nov-2020	2	Updated Figure 1. Safe operating area. Minor text changes.

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